
Guest editorial

IMAPS 2019

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the ISHM-Poland Chapter, and from the 1997, it became the IMAPS-Poland Chapter.

The IMAPS is a non-profit making organization whose aim is to spread of knowledge relating to hybrid microelectronics; a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards (PCBs) to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, bringing into formation the IMAPS-CPMT organization.

The 43rd IMAPS Poland International Conference was joined with 13th ELTE 2019 Conference and it was organized by Wrocław University of Technology. This joined event took place between 4 and 6 September 2019. The scope of the Conference covered everything in electronics between the chip and the system. Both conferences were attended by 102 participants, including 9 guests from abroad. During the Conference, 17 invited lectures, 25 regular lectures and 54 posters were presented. The conference was supported by four international journals indexed in Journal Citation Report database and two journals indexed in Scopus.

This year, as in the previous year, two young Scientists have been awarded winning the refund of the conference fee during the next IMAPS 2019 Poland Conference.

In the special issue of *Microelectronics International*, seven papers have been collected. All of them were subjected to the journal's regular reviewing procedure.

First, three papers by Synkiewicz-Musialska, Bartsch *et al.*, Nawrot and Malecha are related to multilayered structures applied in electronics.

In the next paper, Drygała *et al.* deal with TiO₂ Blocking Layers for Dye-Sensitized Solar Cells.

Górecki and Górecki describe the electrothermal model for GaNSchottky diodes. In sixth paper, Firek *et al.* examine the field effect transistor with thin AlOxNy film as gate dielectric.

In the last paper by Gierczak *et al.*, the method of fabrication and characterization of mixed thin-/thick film thermoelectric microgenerator based on constantan/chromium and silver arms is presented.

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Microelectronics International*. I hope that it will be of interest to readers of the journal and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about different technologies and problems related to microelectronics issues. I believe that this branch of science could be effectively developed in the future.

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